



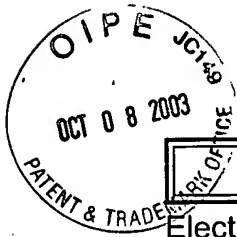
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 49077
Application ID: 10610016
Title of Invention: MAKING THERMALLY ENHANCED
CHIP SCALE LEAD CHIP
SEMICONDUCTOR PACKAGES
First Named Inventor: David McCann
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-10-03
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Statement
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Confirmation number: 1207
Attorney Docket Number: AMKOR038C




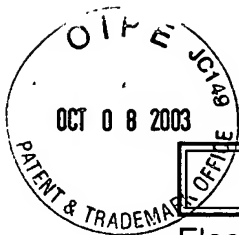
Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
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**TRANSMITTAL**

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	MAKING THERMALLY ENHANCED CHIP SCALE LEAD CHIP SEMICONDUCTOR PACKAGES									
<p>Application Number: 10/610016 </p> <p>Date: 2003-10-03</p> <p>First Named Applicant: David R. McCann</p> <p>Confirmation Number: 1207</p> <p>Attorney Docket Number: AMKOR038C</p>										
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Submitted by:	Elec. Sign.	Sign. Capacity								
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids3-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids3-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids3-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

MAKING THERMALLY ENHANCED CHIP SCALE LEAD
CHIP SEMICONDUCTOR PACKAGES

Application Number: 10/610016



Confirmation Number: 1207

First Named Applicant: David McCann

Attorney Docket Number: AMKOR038C

Art Unit: 2811

Search string: (5673479 or 5683806 or 5689135 or 5696666
or 5701034 or 5703407 or 5710064 or 5723899
or 5736432 or 5745984 or 5753977 or 5766972
or 5770888 or 5776798 or 5783861 or 5801440
or 5814877 or 5814881 or 5814883 or 5814884
or 5817540 or 5818105 or 5821457 or 5821615
or 5834830 or 5835988 or 5844306 or 5856911
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or 5909053 or 5917242 or 5939779 or 5942794
or 5951305 or 5959356 or 5969426 or 5973388
or 5976912 or 5977613).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date